



Material Content Data Sheet



Halogen-Free

Sales Product Name	IR35411MTRPBF	Issued	08. February 2022
MA#	MA004396760		
Package	PG-IQFN-39-13	Weight*	112.43 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.538	1.37	1.37	13682	13682
chip_2	inorganic material	silicon	7440-21-3	0.261	0.23	0.23	2326	2326
chip_3	inorganic material	silicon	7440-21-3	0.966	0.86	0.86	8591	8591
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		100	
	non noble metal	zinc	7440-66-6	0.045	0.04		401	
	non noble metal	iron	7439-89-6	0.901	0.80		8014	
	non noble metal	copper	7440-50-8	36.586	32.53	33.38	325410	333925
wire	noble metal	gold	7440-57-5	0.315	0.28	0.28	2799	2799
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		726	
	plastics	epoxy resin	-	4.201	3.74		37367	
	inorganic material	silicondioxide	60676-86-0	36.506	32.47	36.28	324695	362788
leadfinish	noble metal	palladium	7440-05-3	0.003			26	
	noble metal	gold	7440-57-5	0.005			41	
	non noble metal	nickel	7440-02-0	0.084	0.08	0.08	750	817
plating	noble metal	silver	7440-22-4	1.271	1.13	1.13	11307	11307
solder	noble metal	silver	7440-22-4	0.096	0.09		854	
	non noble metal	tin	7440-31-5	0.192	0.17		1707	
	non noble metal	lead	7439-92-1	3.551	3.16	3.42	31581	34142
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008	0.01		69	
	non noble metal	zinc	7440-66-6	0.031	0.03		276	
	non noble metal	iron	7439-89-6	0.620	0.55		5511	
	non noble metal	copper	7440-50-8	25.158	22.38	22.97	223767	229623
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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